# Dossier: Phoenix Semiconductor Corporation

## SBIR Award Details

**Award Title:** N/A

**Amount:** $49,993.00

**Award Date:** 2024-07-22

**Branch:** DLA

## AI-Generated Intelligence Summary

**Company Overview:**

Phoenix Semiconductor Corporation (PSC) is a US-based company specializing in advanced microelectronics packaging and assembly services, focusing on delivering high-reliability solutions for demanding applications in the defense, aerospace, and commercial sectors. They offer a full suite of services, including design, prototyping, manufacturing, testing, and qualification of custom microelectronic packages. PSC aims to solve the increasing demand for smaller, lighter, faster, and more robust microelectronic components capable of withstanding extreme environments. Their unique value proposition lies in their vertically integrated approach, allowing them to control the entire packaging process from design to final testing, ensuring consistent quality, rapid turnaround times, and enhanced supply chain security, particularly crucial for sensitive defense applications.

**Technology Focus:**

* Advanced Packaging: Specializes in System-in-Package (SiP), Multi-Chip Module (MCM), and 3D packaging technologies, enabling higher density and improved performance for integrated circuits.
* High-Reliability Solutions: Provides hermetic and non-hermetic packaging solutions that meet stringent military and aerospace standards (e.g., MIL-STD-883, space-level screening). PSC supports various package types including QFN, LGA, BGA and custom packages.

**Recent Developments & Traction:**

* February 2023:\*\* PSC signed a Strategic Partnership Intermediary (SPI) Agreement with the Pennsylvania Department of Community and Economic Development (DCED) to help increase investment in advanced electronics manufacturing capabilities.
* November 2023:\*\* PSC was recognized with a US Department of Commerce Commercial Service Export Achievement Certificate for significantly expanding its export sales in the past 3 years.
* November 2022:\*\* PSC announced the completion of its state-of-the-art high reliability packaging facility, expanding its capacity for advanced microelectronics packaging in support of the defense industrial base.

**Leadership & Team:**

* Dr. Brian D. Hishmeh:\*\* CEO, President and Director. Has a PhD in Electrical Engineering and extensive experience in microelectronics, including holding prior senior management positions in semiconductor manufacturing and design companies.
* Dr. David Harburg:\*\* Co-Founder and Chief Operating Officer.

**Competitive Landscape:**

* Mercury Systems:\*\* Mercury Systems offers a wider range of defense electronics solutions. PSC differentiates itself through its dedicated focus and expertise in advanced microelectronics packaging and assembly.
* Micross Components:\*\* While Micross Components offers a broader range of microelectronic components and services, PSC focuses specifically on advanced, custom packaging solutions, emphasizing faster turnaround and a more vertically integrated approach.

**Sources:**

1. [https://phoenixsemi.com/](https://phoenixsemi.com/)

2. [https://www.prnewswire.com/news-releases/psc-announces-strategic-partnership-agreement-with-the-pennsylvania-department-of-community-and-economic-development-301741676.html](https://www.prnewswire.com/news-releases/psc-announces-strategic-partnership-agreement-with-the-pennsylvania-department-of-community-and-economic-development-301741676.html)

3. [https://www.trade.gov/success-stories/phoenix-semiconductor-corporation](https://www.trade.gov/success-stories/phoenix-semiconductor-corporation)

4. [https://www.mddionline.com/products/microelectronics/phoenix-semiconductor-corporation-builds-state-art-high-reliability-packaging](https://www.mddionline.com/products/microelectronics/phoenix-semiconductor-corporation-builds-state-art-high-reliability-packaging)